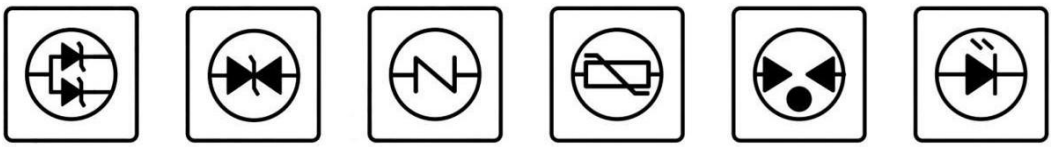
MSKSEMI 美森科
SEMICONDUCTOR



KBP3005-MS THRU KBP310-MS

Product specification

VOLTAGE RANGE: 50 - 1000V
CURRENT: 3.0 A

FEATURES

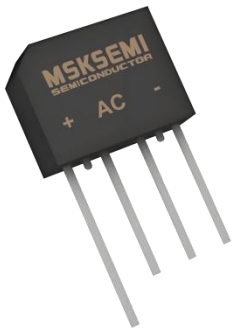
- Surge overload rating-80 amperes peak
- Ideal for printed circuit board
- Plastic material has Underwriters Labooratory
- Flammability Classification 94V-O
- Mounting position: Any
- Lead: Silver Plated Cooper Lead.

MECHANICAL DATA

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 1.7 grams (approx.)
- Mounting Position: Any
- Marking: Type Number

REFERENCE NEWS

KBP



Marking

KBP3005-MS	KBP301-MS	KBP302-MS	KBP304-MS
MSKSEMI KBP3005 + AC -	MSKSEMI KBP301 + AC -	MSKSEMI KBP302 + AC -	MSKSEMI KBP304 + AC -
KBP306-MS	**KBP308-MS**	**KBP310-MS**	
MSKSEMI KBP306 + AC -	MSKSEMI KBP308 + AC -	MSKSEMI KBP210 + AC -	

Maximum Ratings @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	KBP 3005-MS	KBP 301-MS	KBP 302-MS	KBP 304-MS	KBP 306-MS	KBP 308-MS	KBP 310-MS	Unit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Bridge Input Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	60	100	200	400	600	800	1000	V
Maximum Average Forward Output Current @ TA=25 °C	$V_{(AV)}$	3.0							A
Peak Forward Surge Current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	80							A
Maximum DC Forward Voltage drop per element at 1.0A DC	V_F	1.1							V
Maximum DC Reverse Current at rated @TA=25 °C DC Blocking Voltage Per Element @ TA=100°C	I_R	10 1							u A mA
I^2t Rating for fusing(t<8.3ms)	I^2t	10							A^2S
Operating Temperature Range	T_J	-55 to +125							°C
Storage Temperature Range	T_{STG}	-55 to +150							°C

RATING AND CHARACTERISTIC CURVES (KBP3005-MS THRU KBP310-MS)

Fig. 1 - DERATING CURVE FOR OUTPUT RECTIFIED CURRENT

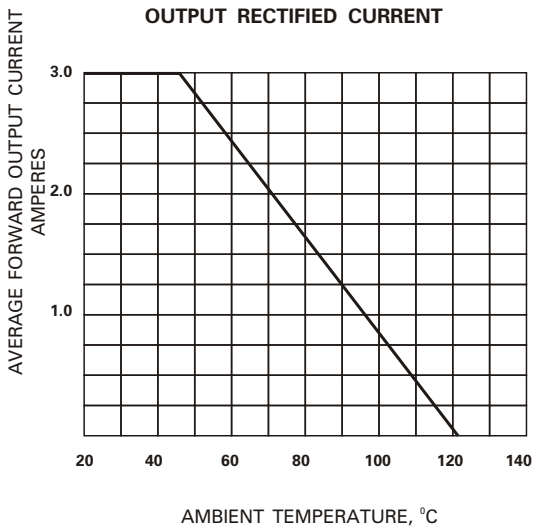


Fig. 2 - DERATING CURVE FOR OUTPUT RECTIFIED CURRENT

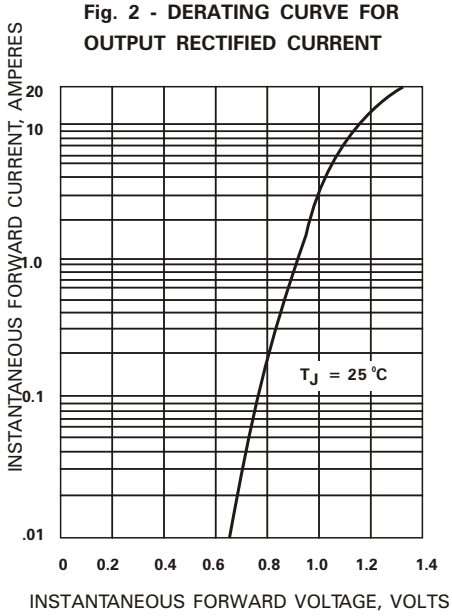


Fig. 3 - TYPICAL FORWARD CHARACTERISTICS

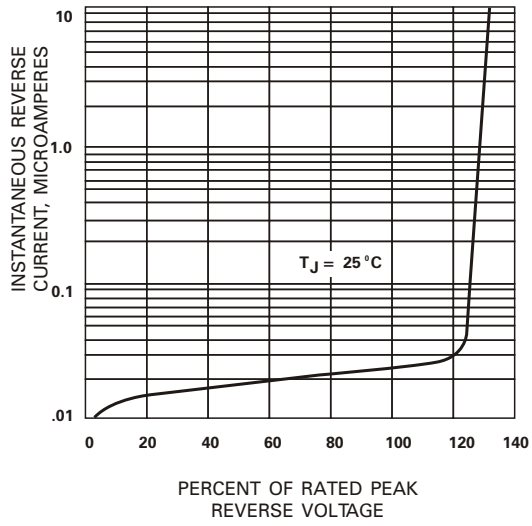
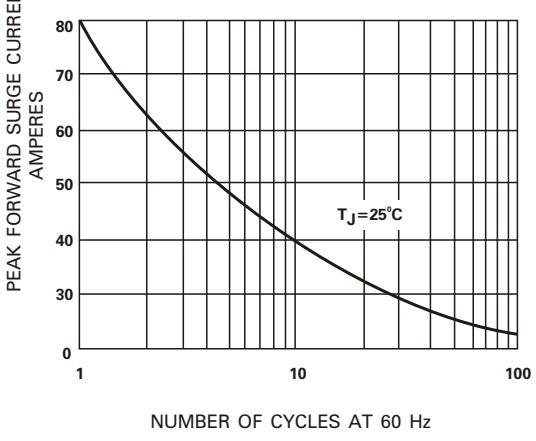
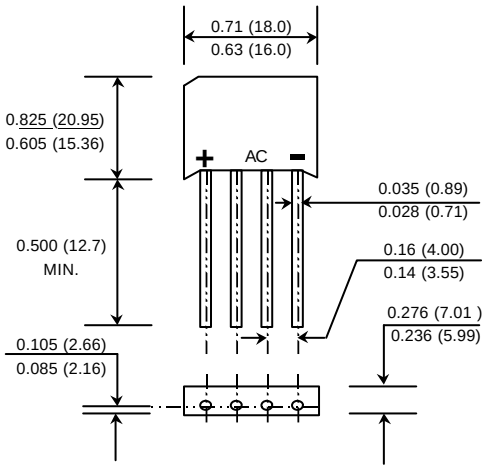


Fig. 4 - MAXIMUM FORWARD SURGE CURRENT



PACKAGE MECHANICAL DATA



Dimensions in inches and (millimeter)

REELSPECIFICATION

P/N	PKG	QTY
KBP3005-MS THRU KBP310-MS	KBP	500

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